

N-Channel 650V (D-S) Super Junction Power MOSFET

PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	650)
R _{DS(on)} at 25 °C (Ω)	V _{GS} = 10 V	0.075

FEATURES

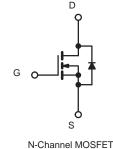
- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Qa)
- Avalanche energy rated (UIS)

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting







Top View

ABSOLUTE MAXIMUM RATINGS (T_C	= 25 °C, unless otherwi	se noted)			
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	650		
Gate-Source Voltage		V _{GS}	± 30	V	
Continuous Dunin Comment (T., 150 °C)	V_{GS} at 10 V $T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 100 ^{\circ}\text{C}$		36		
Continuous Drain Current (T _J = 150 °C)	V_{GS} at 10 V_{C} $T_{C} = 100 ^{\circ}C$	I _D	22	Α	
Pulsed Drain Current ^a		I _{DM}	108		
Linear Derating Factor			1.67	W/°C	
Single Pulse Avalanche Energy b		E _{AS}	1400	mJ	
Maximum Power Dissipation		P _D	210	W	
Operating Junction and Storage Temperature Range	Э	T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	T _J = 125 °C	-1) / / -14	50	\//	
Reverse Diode dV/dt ^d		dV/dt	15	V/ns	
Soldering Recommendations (Peak Temperature) c	for 10 s		260	°C	

- a. Repetitive rating; pulse width limited by maximum junction temperature. b. $V_{DD}=100$ V, starting $T_J=25$ °C, L=30mH, $R_g=25$ Ω , $I_{AS}=13$ A. c. 1.6 mm from case. d. $I_{SD} \le I_D$, dI/dt=100 A/µs, starting $T_J=25$ °C.



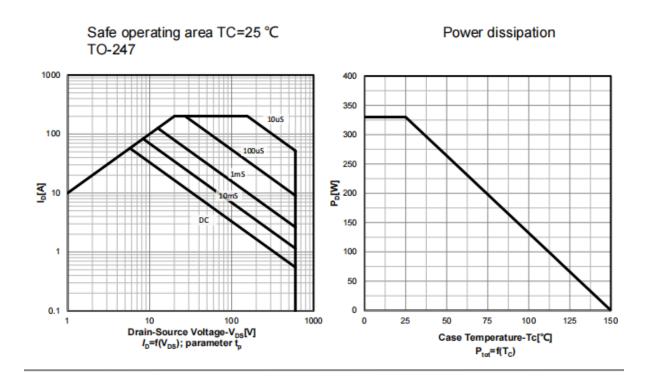
THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	-	0.38	C/VV

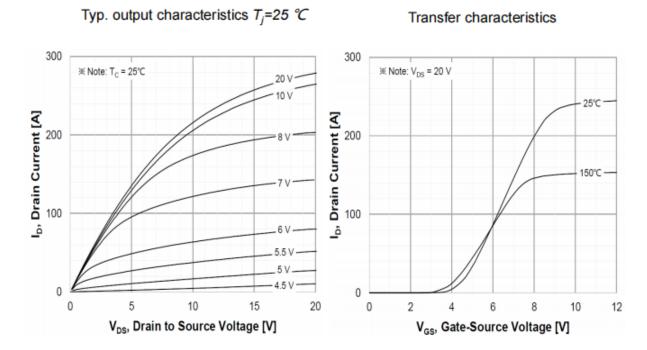
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		•					•
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 1 mA	650	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	0.70	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.5	-	4.5	V
			V _{GS} = ± 20 V	-	-	± 100	nA
Gate-Source Leakage	I_{GSS}		V _{GS} = ± 30 V	_	-	± 1	μA
			= 650V, V _{GS} = 0 V	_	-	1	
Zero Gate Voltage Drain Current	I _{DSS}		/, V _{GS} = 0 V, T _J = 125 °C	_	-	100	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D =12A	-	0.075	-	Ω
Forward Transconductance	9fs	V _{DS}	= 30 V, I _D = 12A	-	5.6	-	S
Dynamic		,					
Input Capacitance	C _{iss}		V _{GS} = 0 V,	-	3900	-	
Output Capacitance	Coss	1	$V_{DS} = 100 \text{ V},$	-	330	-	
Reverse Transfer Capacitance	C _{rss}	1	f = 1 MHz	-	4	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V _{DS} = 0 V to 520 V, V _{GS} = 0 V		-	63	-	pF
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	213	-	
Total Gate Charge	Qg			-	60	-	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 20 \text{ A}, V_{DS} = 520 \text{ V}$	-	39	-	nC
Gate-Drain Charge	Q _{gd}	1		-	4 7	-	
Turn-On Delay Time	t _{d(on)}			-	18	25	
Rise Time	t _r	$V_{DD} = 520 \text{ V}, I_D = 20\text{A},$		-	24	55	no
Turn-Off Delay Time	t _{d(off)}			-	8 0	-	ns
Fall Time	t _f	V_{GS} = 10 V, R_g = 9.1 Ω		-	1 2	-	
Gate Input Resistance	R_g	f = 1 MHz, open drain		-	0.8	-	Ω
Drain-Source Body Diode Characteristic	S						
Continuous Source-Drain Diode Current	I _S	MOSFET sym	MOSFET symbol showing the		-	36	_
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	108	Α
Diode Forward Voltage	V _{SD}	T _J = 25 °	C, I _S = 8 A, V _{GS} = 0 V	-	-	1.5	V
Reverse Recovery Time	t _{rr}	-		_	520	-	ns
Reverse Recovery Charge	Q _{rr}	T _J = 25 °C, I _F = I _S = 8 A, dl/dt = 100 A/μs, V _R = 400 V		-	5.8	_	μC
Reverse Recovery Current	I _{RRM}				4 5		A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .





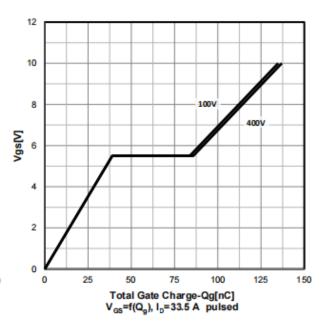




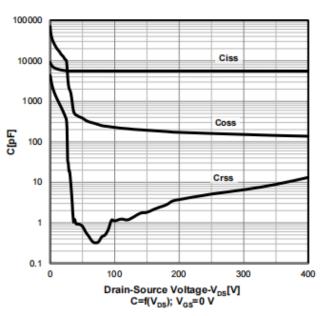
Typ. drain-source on-state resistance

80
70
60
60
40
30
20
0 15 30 45 60 75 90
Drain-Source Current-I_D[A]
R_{DS}(on)=f(I_D); parameter: V_{GS}

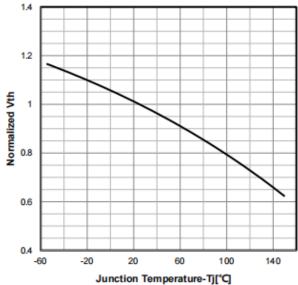
Typ. gate charge characteristics



Typ. capacitances



Normalized $V_{\text{GS(th)}}$ characteristics

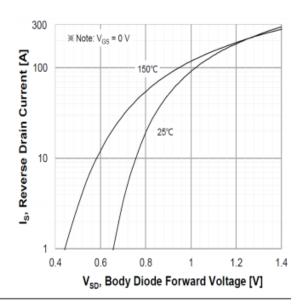




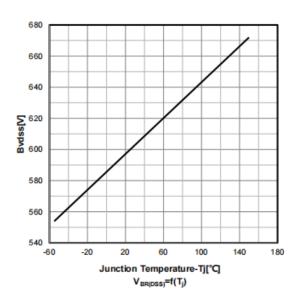
On-resistance vs temperature

120 100 80 40 40 20 40 Junction Temperature-Tj[°C] R_{DS}(on)=f(T_j); I_p=33.5 A; V_{GS}=10 V

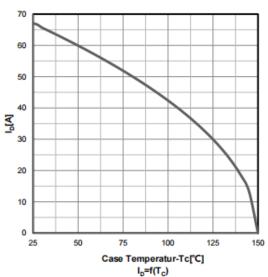
Forward characteristics of reverse diode



Drain-source breakdown voltage



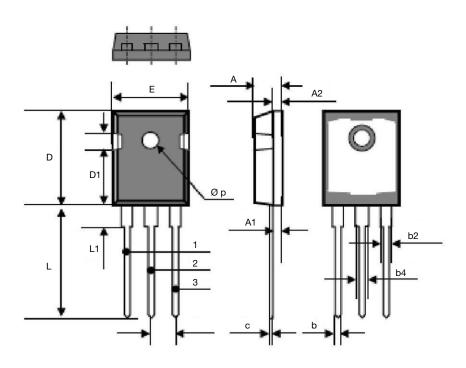
Drain current vs temperature



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TO-247



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
Α	4.70	5.31	0.185	0.209
A1	2.21	2.59	0.087	0.102
A2	1.50	2.49	0.059	0.098
b	0.99	1.40	0.039	0.055
b2	1.65	2.41	0.065	0.095
b4	2.59	3.43	0.102	0.135
С	0.61 BSC		0.024 BSC	
D	20.80	21.46	0.819	0.845
D1	3.68	5.49	0.145	0.216
(e)	5.46 BSC		0.215 BSC	
Е	15.49	16.26	0.610	0.640
L	19.81	20.32	0.780	0.800
L1	4.06	4.50	0.160	0.177
Øр	3.51	3.66	0.138	0.144



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